

BOARD OF GOVERNORS (Continued)

Secretary
VACANT

Treasurer
JOHN M. SEGELKEN
Consultant
14 Cedar Island Drive
Brick, NJ 08723
(732) 920-3023
j.segelen@ieee.org

Through 2005
W. T. CHEN
L. LI
L. M. PALMER
W. J. TRYBULA
E. J. VARDAMAN
D. WHALLEY

Through 2006
E. SUHIR
T. G. REYNOLDS, III
P. C. H. CHAN
J. LIU
W. D. BROWN
C. LEE

Through 2007
E. O. BEYNE
S. J. BEZUK
N. RAO BONDA
R. CHANCHANI
K. PEARSALL
C. P. WONG

Ex Officio

R. W. WYNDRUM, JR., Senior Past President
J. W. STAFFORD, JR., Junior Past President

Standing Committees

Academic Affairs: O. A. PALUSINSKI
Awards: R. BONDA
Chapter Development: R. W. RUSSELL, II
Constitution and Bylaws: T. MAK
Distinguished Speakers: A. F. PUTTLITZ
Educational Activities: VACANT
Fellows: C. P. WONG
Fellows Search: D. PALMER AND R. TUMMALA
Finance: R. TUMMALA
Intersociety Liaison: VACANT
Long Range Planning/Strategic Planning: J. W. STAFFORD
Membership: R. W. RUSSELL, II
Newsletter Editor: D. W. PALMER
Nominations: J. SEGELKEN
Publicity: VACANT
Standards: J. W. BALDE
Strategic Planning: R. W. WYNDRUM, JR.

Technical Committees

Electrical Contacts, Connectors, and Cable: J. WITTER
Discrete and Integral Passive Components: L. SCHAPER
IC and Package Assembly: VACANT
Manufacturing – Design and Process: W. TRYBULA
Materials: R. CHANCHANI
High Density PWB Packaging: Y. FUKUOKA
Environmental Stress and Reliability Test: M. GIBBEL
Thermal Management and Thermomechanical Design: T. MAK
Fiber Optics and Photonics: S. LAW
Electrical Test: B. KIM
Electrical Design, Modeling, and Simulation: M. SWAMINATHAN
Power Electronic Packaging (joint with Power Electronics Society): D. HOPKINS
Systems Packaging (joint with Computer Society): J. SEGELKEN/C. SWAGER
RF and Wireless: C. GAW
MEMS and Sensor Packaging: E. JUNG
Wafer Level Packaging: M. TOEPPER
Education: R. TUMMALA
Green Electronics, Manufacturing and Packaging: H. GRIESE
Electronic Manufacturing Services: S. RAO
Nanopackaging: R. TUMMALA

Chapters

Atlanta	Minsk, Belarus
Bangalore	Nizhny Novgorod (Russia)
Binghamton	Novosibirsk (Russia)
Beijing	Oregon
Boston	Orlando
Bulgaria	Philadelphia
Central Ukraine (Kiev)	Phoenix
Chicago	San Diego
Daejeon (Korea)	Santa Clara Valley
Finland	Saratov-Penza
France	Singapore
Germany	Sweden
Greece	Switzerland
Hong Kong	Taipei
Hungary/Romania	Tokyo
India	Toronto
Los Angeles	United Kingdom & Republic of Ireland
Malaysia	West Ukraine (Lviv)

Strategic Program Directors

Awards and Recognition: N. R. BONDA
Conferences: S. W. R. LEE
ECTC Integration: C. P. WONG
Educational Programs: A. F. PUTTLITZ
Industry Programs: J. W. STAFFORD
Global Chapters and Membership: R. W. RUSSELL, II
Marketing: C. SWAGER
Publications: P. B. WESLING
Student Programs: W. D. BROWN
Technical Programs: R. ASCHENBRENNER
European Programs: J. LIU
Asian Programs: W. T. CHEN

INSTITUTIONAL LISTINGS

The IEEE Components, Packaging, and Manufacturing Technology Society is grateful for the assistance given by the firms listed below and invites application for Institutional Listings from other firms interested in the fields of parts, electrical contacts, process development and control, electronic materials, and electronics production methods and techniques.

An Institutional Listing recognizes contributions to support the publication of the IEEE TRANSACTIONS ON ELECTRONICS PACKAGING MANUFACTURING. Minimum rates are \$100.00 for four consecutive issues, \$200.00 for eight. Larger contributions will be most welcome. No agency fee is granted for soliciting such contributions. Inquiries, or contributions made payable to IEEE, plus instructions on how you wish your Institutional Listing to appear, should be sent to Finance Administrator, IEEE Technical Activities, 445 Hoes Lane, Piscataway, NJ 08855-1331.